

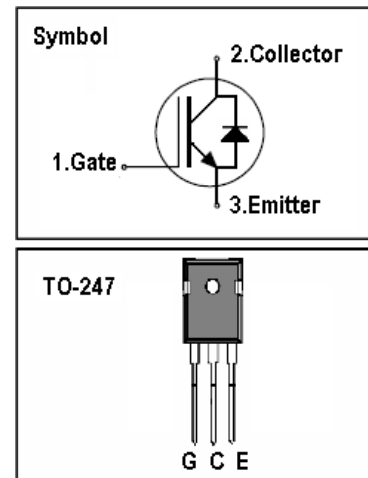
IGBT

Features

- 650V 30A, $V_{CE(sat)(typ.)} = 1.7V@30A$
- Field Stop IGBT Technology.
- 10 μ s Short Circuit Capability.
- Square RBSOA.
- Positive VCE (on) Temperature Coefficient.

Benefits

- High Efficiency for Motor Control.
- Rugged Performance.
- Excellent Current Sharing in Parallel Operation



Ordering Information

| Part Number | Package | Marking |
|-------------|---------|------------|
| CXG30N65HS | TO-247 | DXG30N65HS |

Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|-----------|--|-------------|------------|
| V_{CES} | Collector-Emitter Voltage | 650 | V |
| V_{GES} | Gate-Emitter Voltage | ± 30 | V |
| I_C | Continuous Collector Current ($T_C=25^\circ C$) | 60 | A |
| | Continuous Collector Current ($T_C=100^\circ C$) | 30 | A |
| I_{CM} | Pulsed Collector Current (Note 1) | 120 | A |
| I_F | Diode Continuous Forward Current ($T_C=100^\circ C$) | 30 | A |
| I_{FM} | Diode Maximum Forward Current (Note 1) | 120 | A |
| t_{sc} | Short Circuit Withstand Time | 10 | us |
| I_{sc} | Short Circuit Current | 200 | A |
| P_D | Maximum Power Dissipation ($T_C=25^\circ C$) | 250 | W |
| P_D | Maximum Power Dissipation ($T_C=100^\circ C$) | 100 | W |
| T_J | Operating Junction Temperature Range | -55 to +150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to +150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Max. | Units |
|---------------|--|------|--------------|
| $R_{th\ j-c}$ | Thermal Resistance, Junction to case for IGBT | 0.50 | $^\circ C/W$ |
| $R_{th\ j-c}$ | Thermal Resistance, Junction to case for Diode | 0.96 | $^\circ C/W$ |
| $R_{th\ j-a}$ | Thermal Resistance, Junction to Ambient | 80 | $^\circ C/W$ |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|---------------|--------------------------------------|--|------|------|------|----------|
| BV_{CES} | Collector-Emitter Breakdown Voltage | $V_{GE}=0V, I_C=250\mu A$ | 650 | - | - | V |
| I_{CES} | Collector-Emitter Leakage Current | $V_{CE}=650V, V_{GE}=0V$ | - | - | 250 | μA |
| I_{GES} | Gate Leakage Current, Forward | $V_{GE}=30V, V_{CE}=0V$ | - | - | 100 | nA |
| | Gate Leakage Current, Reverse | $V_{GE}=-30V, V_{CE}=0V$ | - | - | -100 | nA |
| $V_{GE(th)}$ | Gate Threshold Voltage | $V_{GE}=V_{CE}, I_C=250\mu A$ | 4.0 | - | 5.5 | V |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $V_{GE}=15V, I_C=30A$ | - | 1.7 | 2.0 | V |
| Q_g | Total Gate Charge | $V_{CC}=480V$ $V_{GE}=15V$ $I_C=30A$ | - | 120 | | nC |
| Q_{ge} | Gate-Emitter Charge | | - | 16 | | nC |
| Q_{gc} | Gate-Collector Charge | | - | 63 | | nC |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{CC}=400V$ $V_{GE}=15V$ $I_C=30A$ $R_G=10\Omega$ Inductive Load $T_C=25^\circ\text{C}$ | - | 25 | - | ns |
| t_r | Turn-on Rise Time | | - | 36 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 121 | - | ns |
| t_f | Turn-off Fall Time | | - | 25 | - | ns |
| E_{on} | Turn-on Switching Loss | | - | 0.75 | - | mJ |
| E_{off} | Turn-off Switching Loss | | - | 0.37 | - | mJ |
| C_{ies} | Input Capacitance | $V_{CE}=25V$ | - | 1480 | - | pF |
| C_{oes} | Output Capacitance | $V_{GE}=0V$ | - | 168 | - | pF |
| C_{res} | Reverse Transfer Capacitance | $f=1\text{MHz}$ | - | 65 | - | pF |
| R_{Gint} | Integrated gate resistor | $f=1\text{MHz}, V_{pp}=1V$ | | 1.5 | | Ω |

Electrical Characteristics of Diode ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|-----------|-------------------------------------|----------------------------|------|------|------|-------|
| V_F | Diode Forward Voltage | $I_F=30A$ | - | 1.50 | | V |
| t_{rr} | Diode Reverse Recovery Time | $V_{CE}=400V$ $I_F=30A$ | - | 71 | | ns |
| I_{rrm} | Diode peak Reverse Recovery Current | | - | 24 | | A |
| Q_{rr} | Diode Reverse Recovery Charge | $dI_F/dt=1000A/\mu s$ | - | 1038 | | nC |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

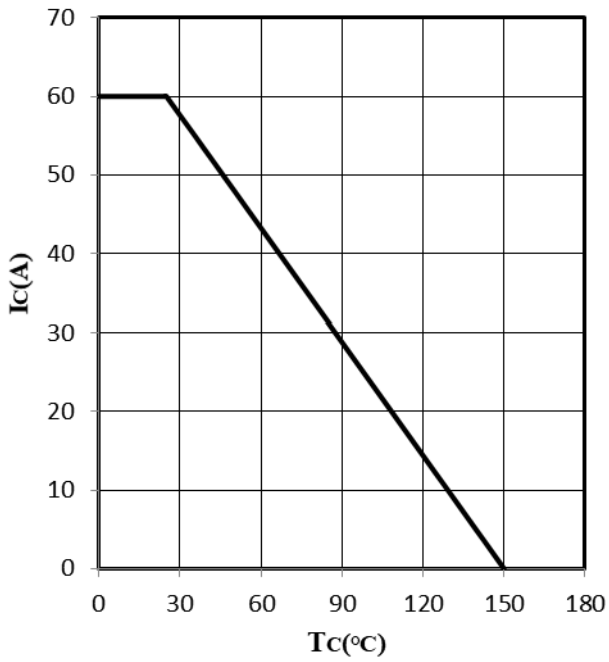


Fig 1. DC Collector current as a function of case temperature ($V_{GE} \geq 15V$, $T_j \leq 150^\circ C$)

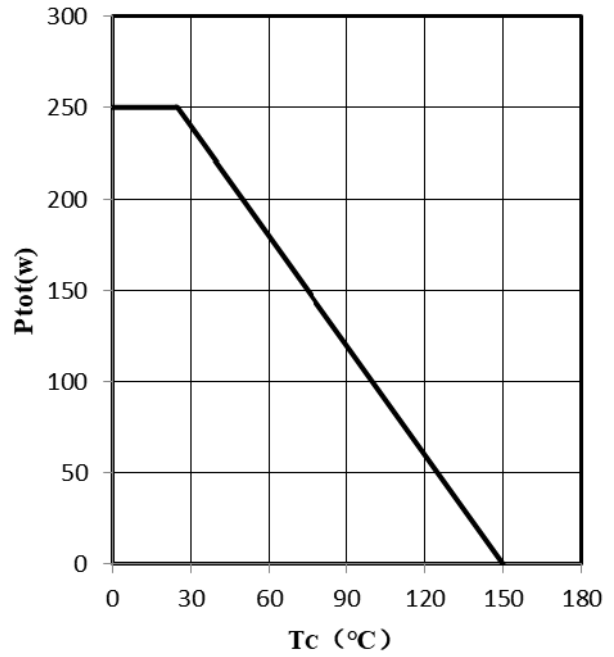


Fig 2. Power dissipation as a function of case temperature ($T_j \leq 150^\circ C$)

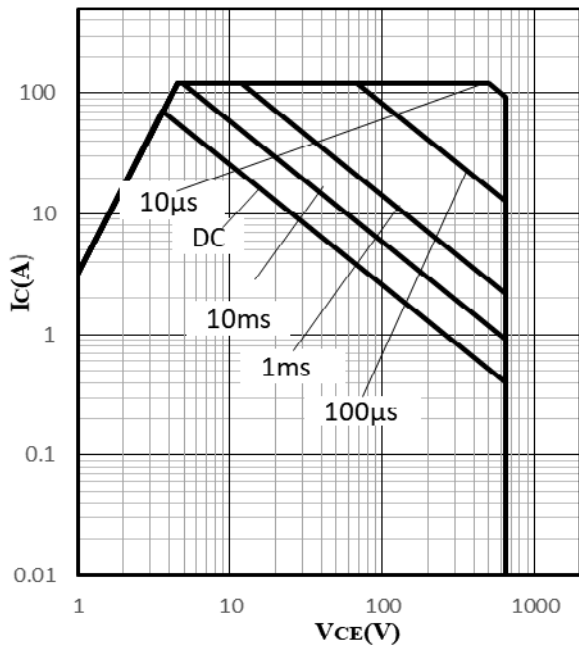


Fig 3. IGBT Forward safe operation area

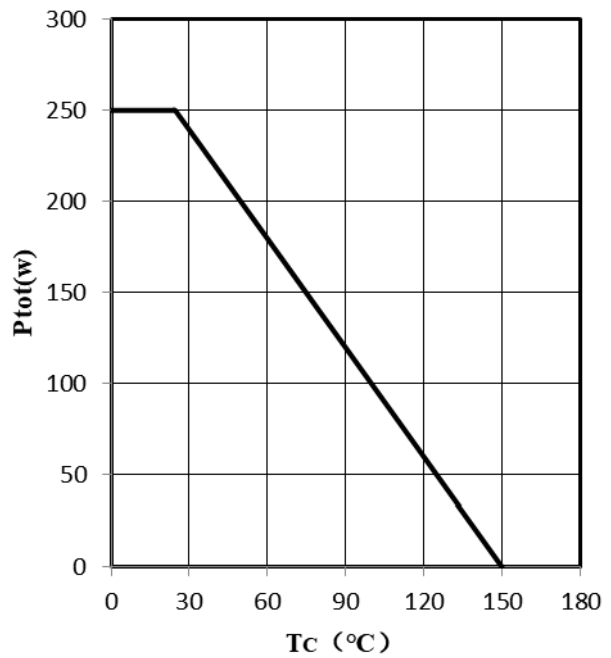


Fig 4. IGBT Reverse safe operation area

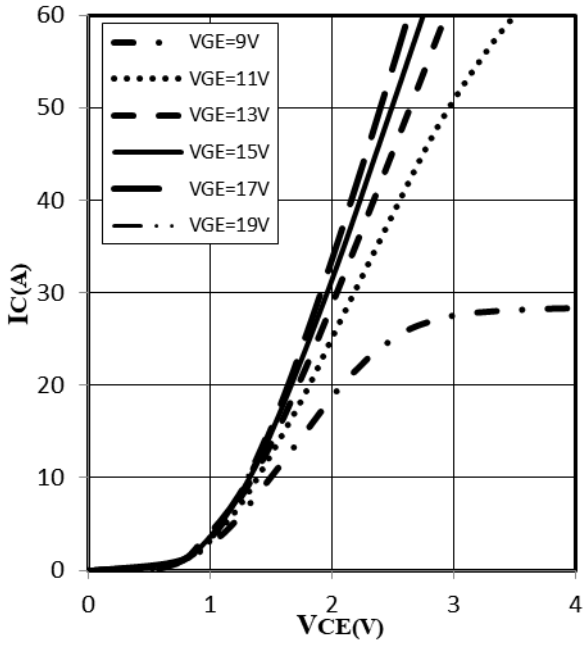


Fig 5. Typical output characteristic ($T_j=25^\circ\text{C}$)

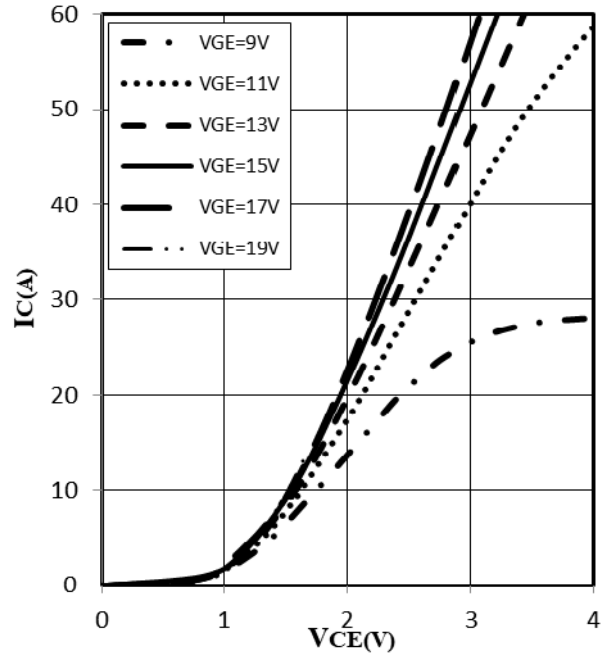


Fig 6. Typical output characteristic ($T_j=125^\circ\text{C}$)

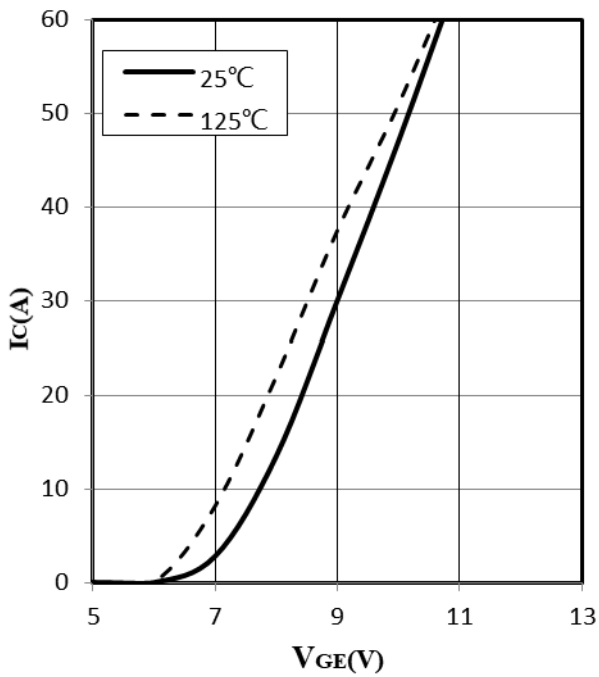


Fig 7. Typical transfer characteristic ($V_{CE}=20\text{V}$)

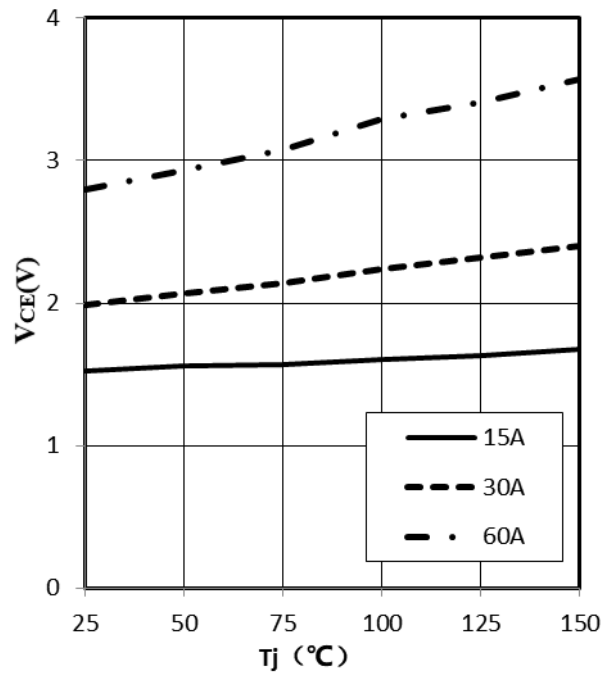


Fig 8. Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15\text{V}$)

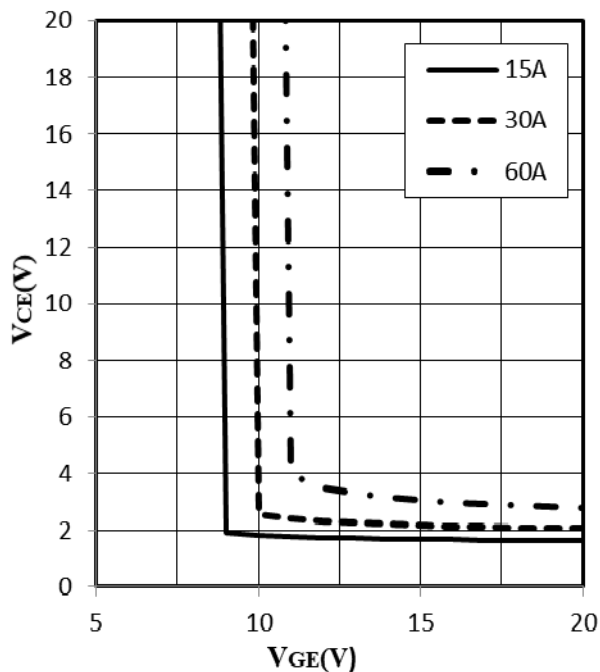


Fig 9. Typical collector-emitter saturation voltage as a function of V_{GE} ($T_j=25^\circ\text{C}$)

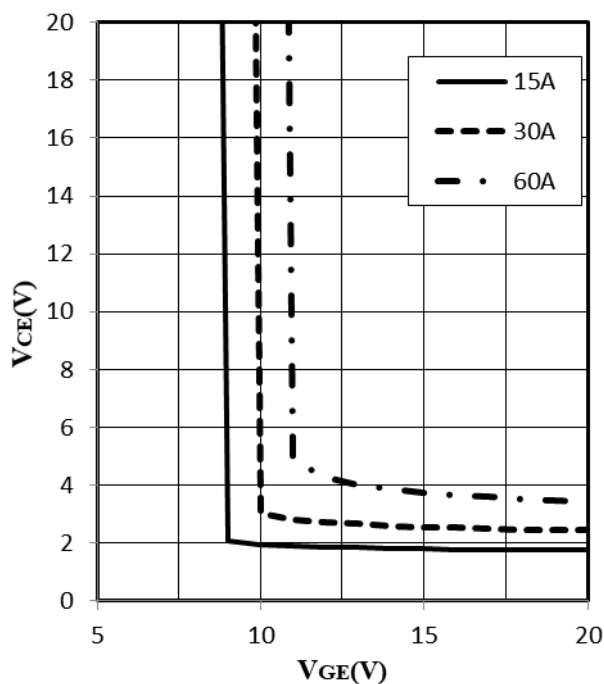


Fig 10. Typical collector-emitter saturation voltage as a function of V_{GE} ($T_j=125^\circ\text{C}$)

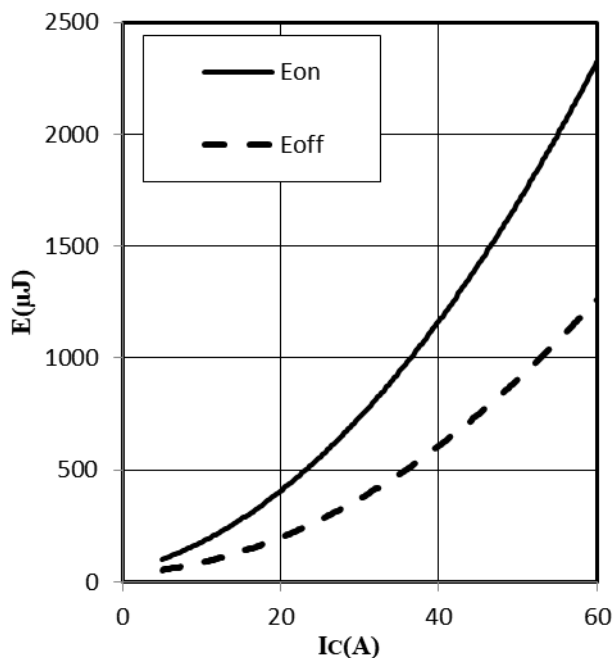


Fig 11. Typical switch energy as a function of I_c (inductive load, $T_j=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15\text{V}$, $R_G=10\Omega$)

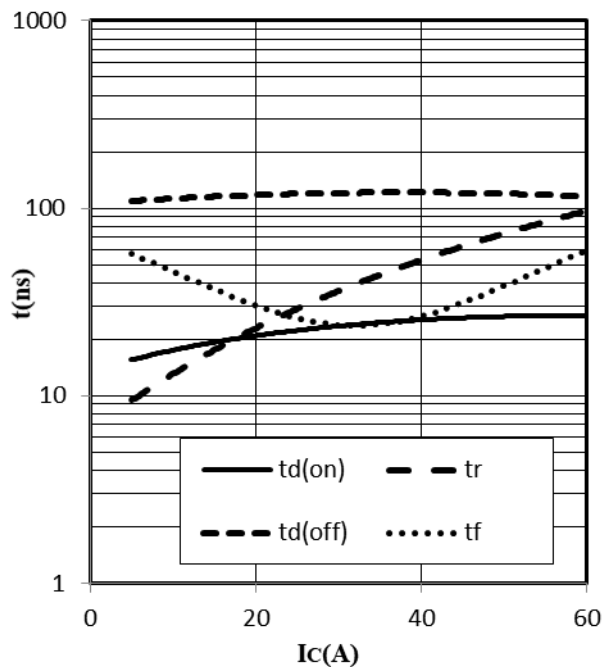


Fig 12. Typical switch time as a function of I_c (inductive load, $T_j=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15\text{V}$, $R_G=10\Omega$)

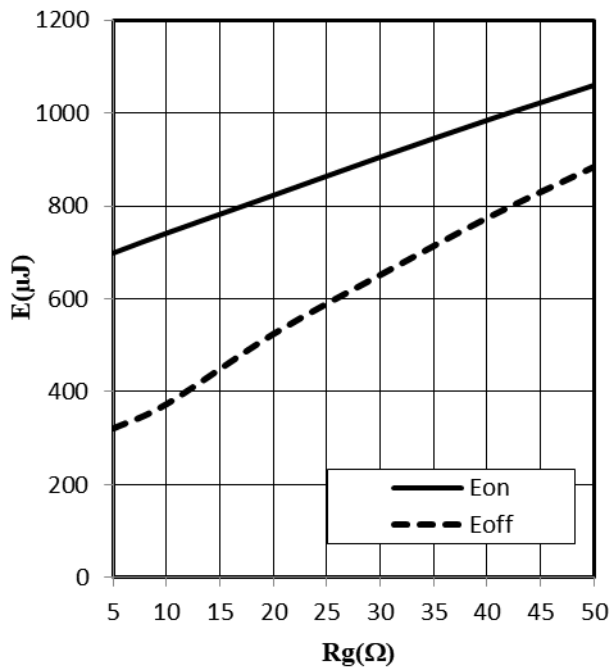


Fig 13. Typical switch energy as a function of R_G
(inductive load, $T_j=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15\text{V}$, $I_c=30\text{A}$)

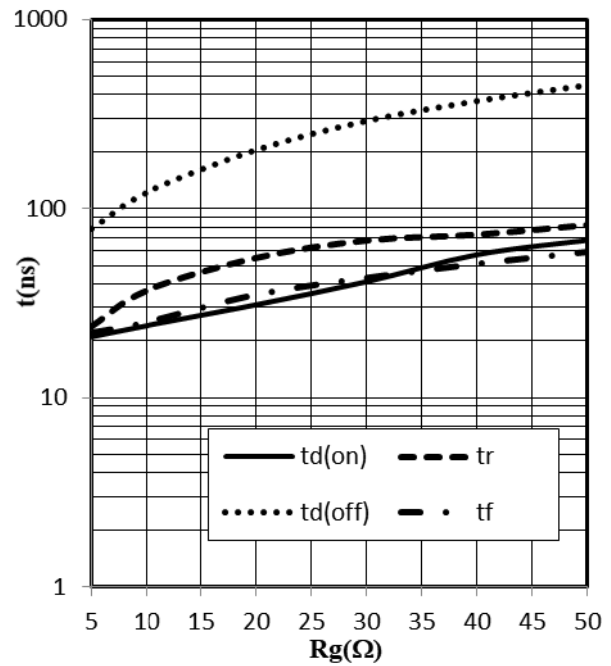


Fig 14. Typical switch time as a function of R_G
(inductive load, $T_j=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15\text{V}$, $I_c=30\text{A}$)

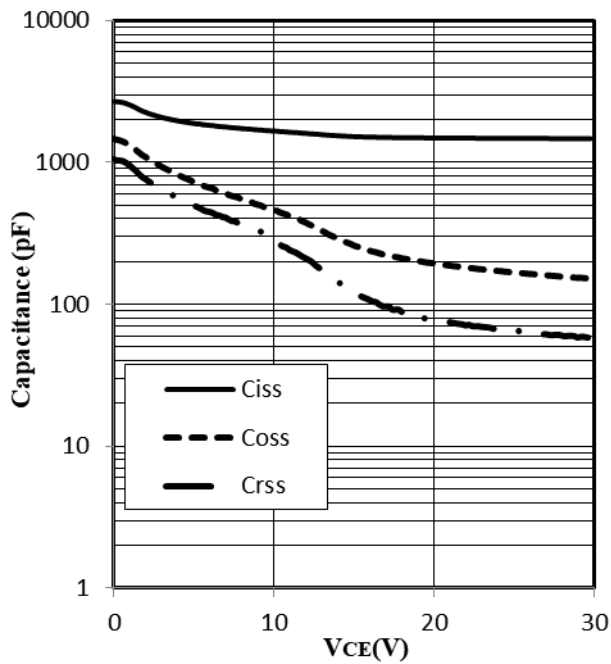


Fig 15. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0\text{V}$, $f=1\text{MHz}$)

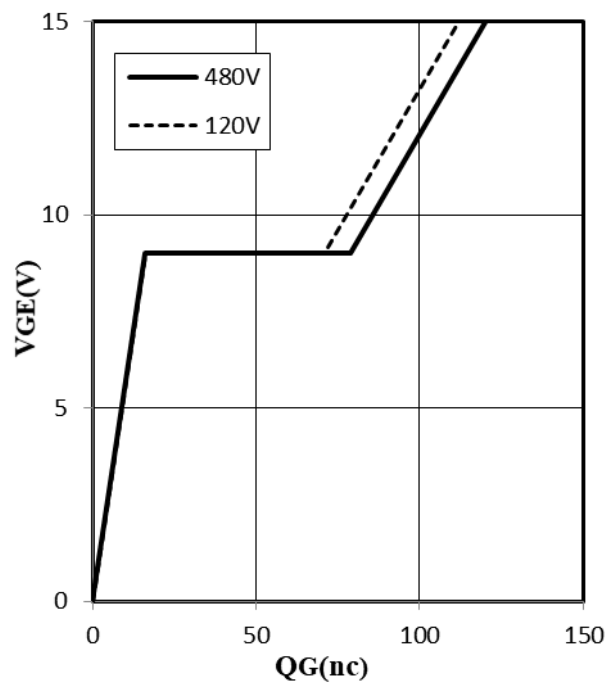


Fig 16. Typical gate charge ($I_c=30\text{A}$)

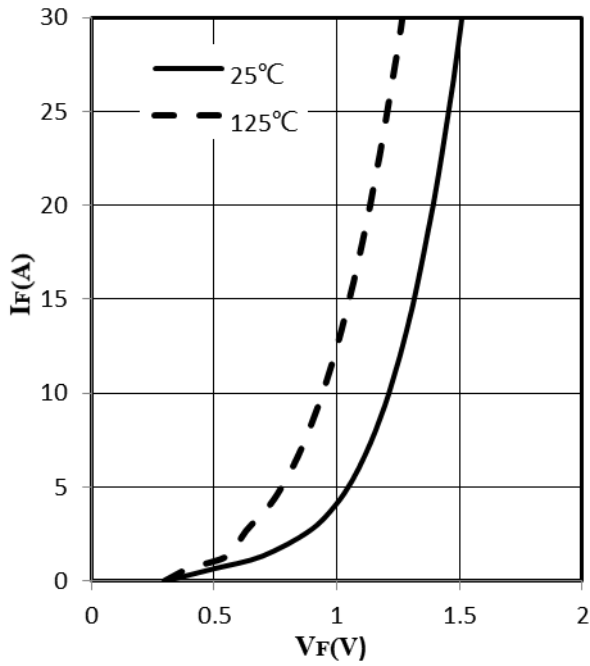


Fig 17. Typical diode forward current as a function of forward voltage

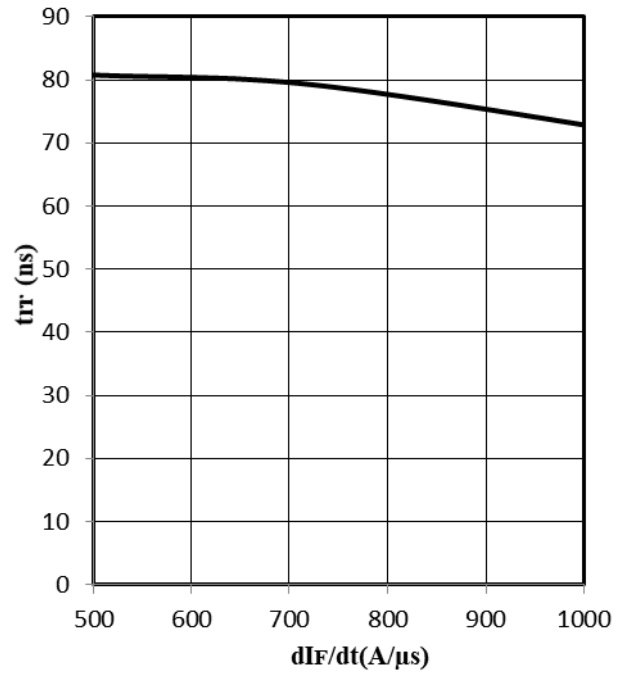


Fig 18. Typical trr as a function of dIF/dt (IF=30A)

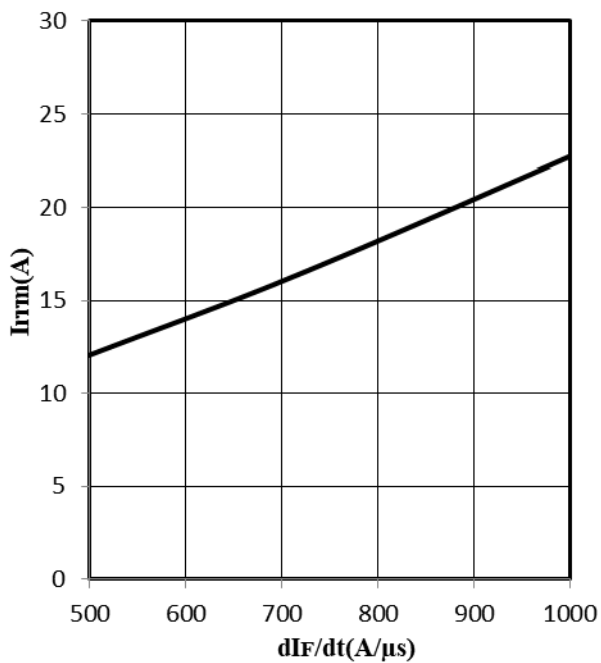


Fig 19. Typical Irms as a function of dIF/dt (IF=30A)

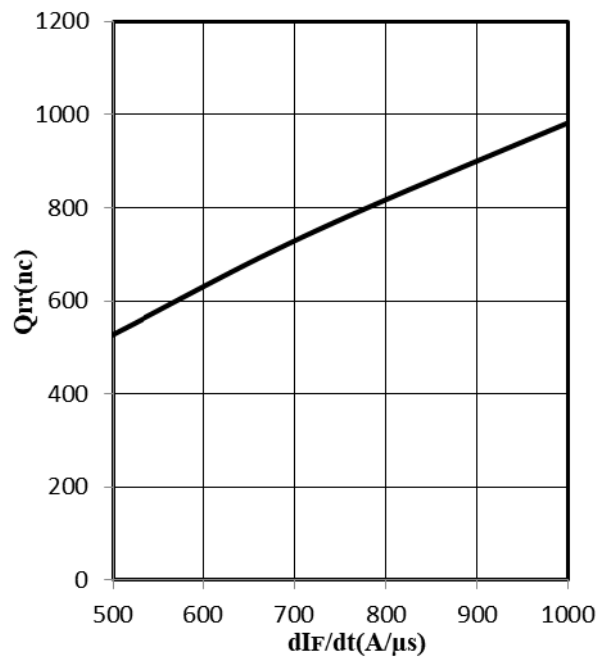


Fig 20. Typical Qrr as a function of dIF/dt (IF=30A)

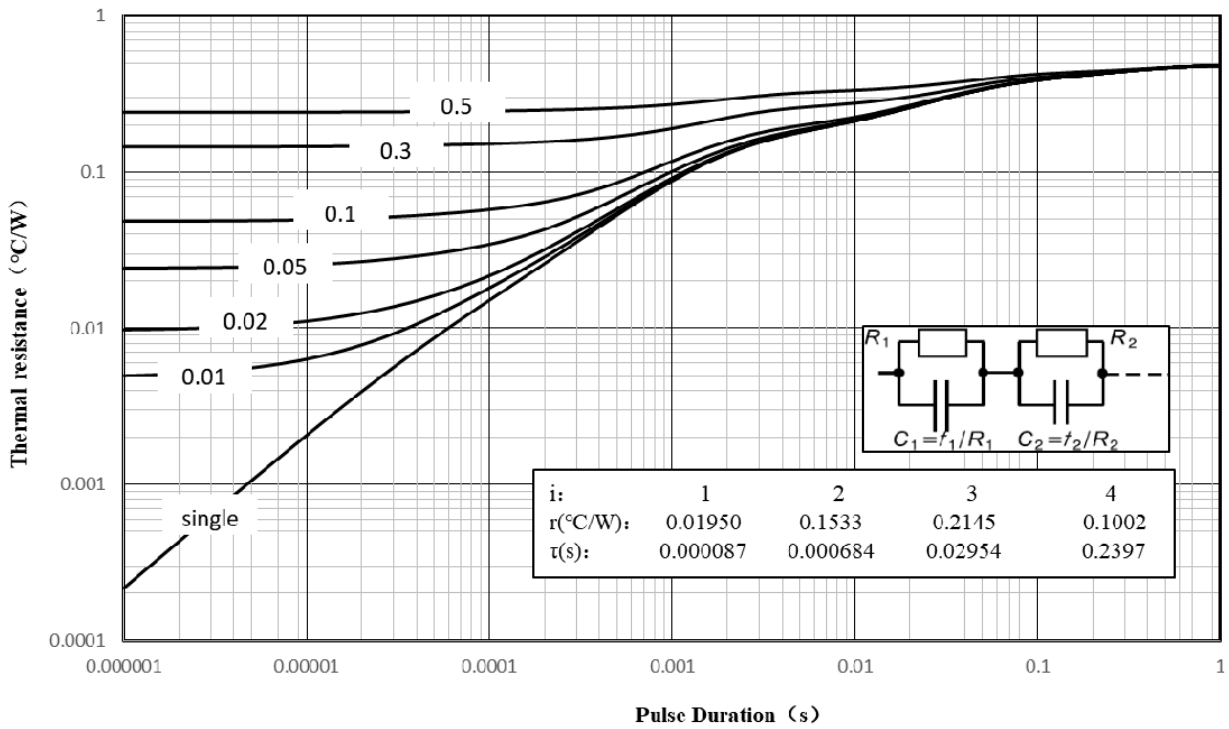


Fig 21. IGBT transient thermal resistance(D=tp/T)

Revision history

| Date | Revision | Changes |
|-------------|----------|-----------------|
| 28-May-2020 | 1.0 | Initial release |

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